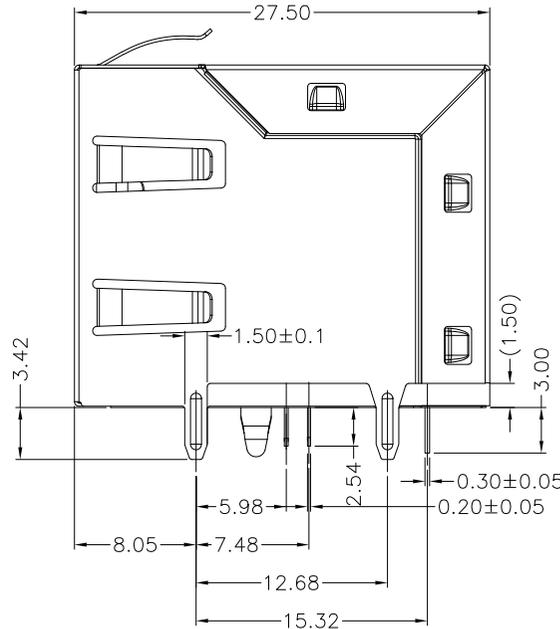
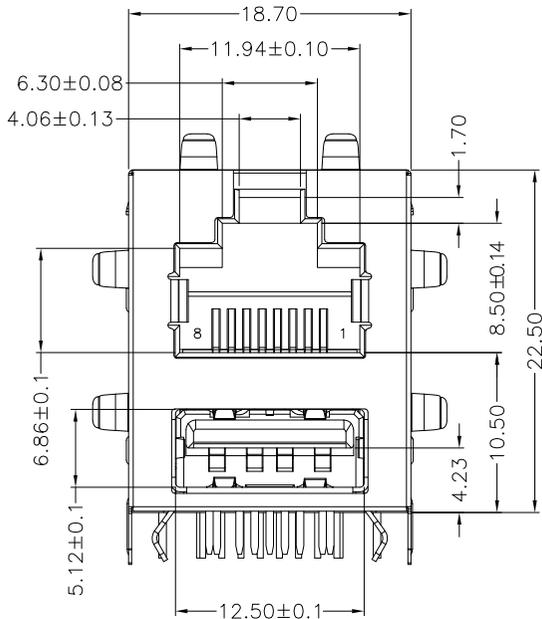
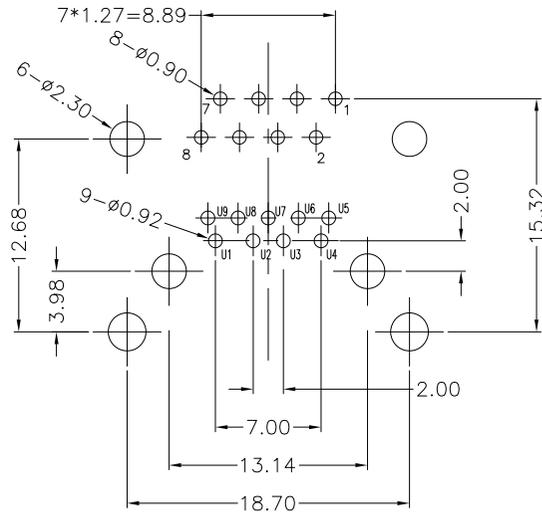
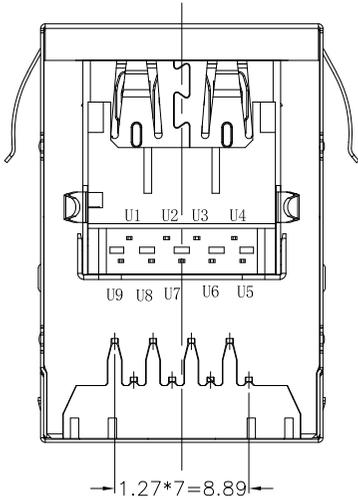


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2018/07/31	Phebe Su
A1			Change shell window	2019/11/13	Phebe Su

1.MECHANICAL DIMENSIONS:

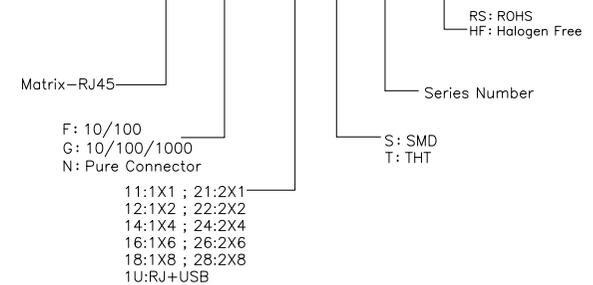


NOTES:

- MATERIALS:
HOUSING: PBT, UL94V-0, BLACK.
RJ CONTACTS: PHOSPHOR BRONZE T=0.30
GOLD 1u" ON CONTACT, TIN PLATING ON SOLDER TAIL
NICKEL PLATING UNDERPLATING.
RJ SHELL: BRASS, NICKEL PLATING OVERALL
USB CONTACTS: BRASS T=0.20
GOLD FLASH ON CONTACT, TIN PLATING ON SOLDER TAIL
NICKEL PLATING UNDERPLATING.
USB SHELL: SPCC, NICKEL PLATING OVERALL
- OPERATING TEMPERATURE: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

MATRIX PART NO:

M R J N - 1 U T 8 9 3 R S



PIN NO.	U1	U2	U3	U4	
SLGNL NAME	V BUS	D-	D+	GND	
REMARK	USB 2.0 CONTACT PINS				
PIN NO.	U5	U6	U7	U8	U9
SLGNL NAME	STDA_SSRX-	STDA_SSRX+	GND_DRAIN	STDA_SSTX-	STDA_SSTX+
REMARK	USB 3.0 CONTACT PINS				

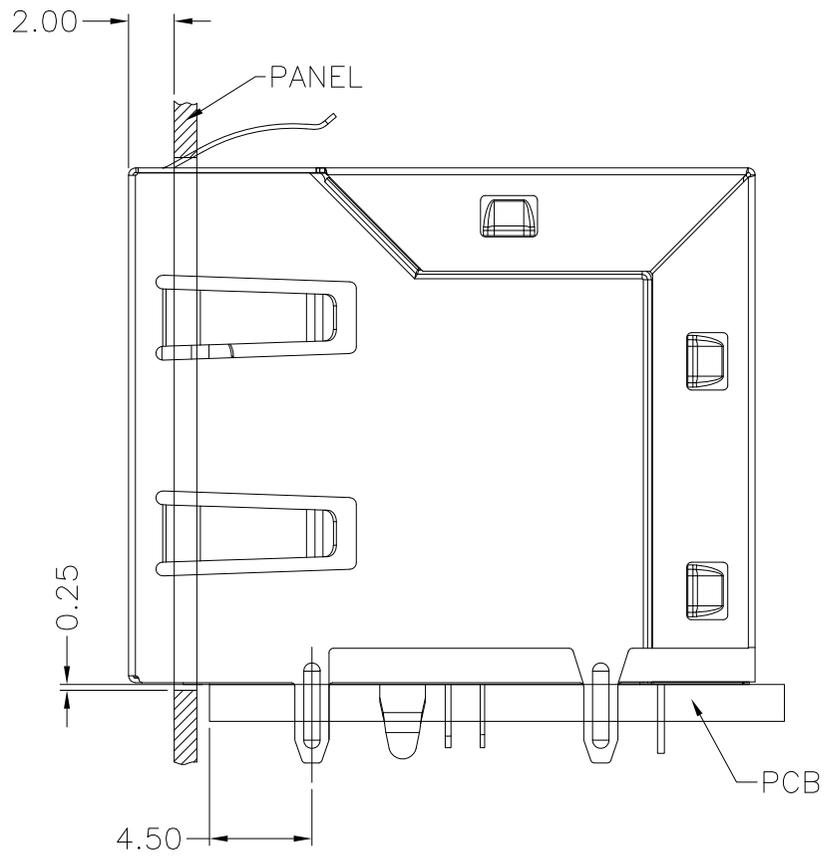
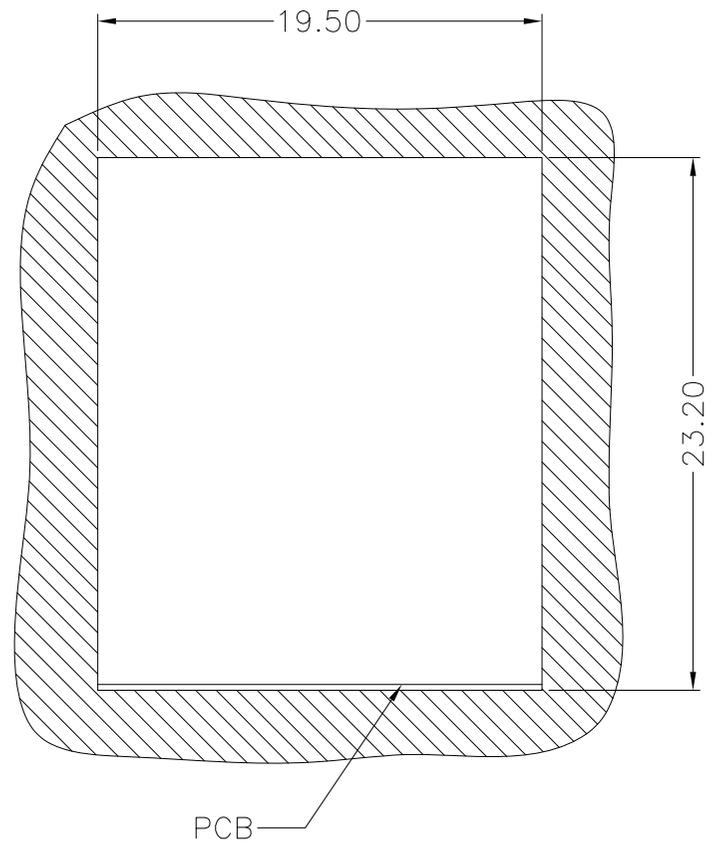


Matrix Electronics Co.,Ltd

TOLERANCE: X:X X:X X:XX X:XXX X $\pm 2^{\circ}$	DESIGN BY : Phebe Su	DATE : 2019/11/13	PART NAME: RJ45+USB3.0 CONN, W/O LED
± 0.38 ± 0.25 ± 0.13	CHECKED BY: Vicky Hsieh	DATE : 2019/11/13	PART NO. MRJN-1UT893RS
	APPROVED BY1: Richard Hsieh	DATE : 2019/11/13	MOLD NO. NA
UNIT: mm [inch]	APPROVED BY2: Richard Hsieh	DATE : 2019/11/13	DRAW NO.
SCALE:1:1	SIZE:A4		SHEET NO. 1 OF 2

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2018/07/31	Phebe Su
A1			Change shell window	2019/11/13	Phebe Su



RECOMMENDED
PANEL CUTOUT DIMENSION



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 X±2°	DESIGN BY : Phebe Su	DATE : 2019/11/13	PART NAME: RJ45+USB3.0 CONN, W/O LED	
	CHECKED BY: Vicky Hsieh	DATE : 2019/11/13	PART NO.	MRJN-1UT893RS
 UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2019/11/13	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2019/11/13	DRAW NO.	SHEET NO.
SCALE:1:1	SIZE:A4			2 OF 2